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(54) IMPROVED SILICON WAFER CLEANING LIQUID

(57) Abstract:

PURPOSE: To prolong service life of an alkaline silicon wafer cleaning liquid by adding surfactant to a cleaning liquid and foaming it to form a bubble layer on the surface thereby preventing ammomia from scattering.

CONSTITUTION: Surfactant is added to an alkaline silicon wafer cleaning liquid composed of ammonia, hydrogen peroxide, and water to form bubbles on the surface of the liquid thus preventing ammonia from scattering. More specifically, a cleaning liquid containing 0.055% of ammonia, 0.05% of hydrogen peroxide, and 0.5% polyoxyethylene nonyl ether is held as it is at 80°C while containing 10ppb of Cu and Fe being mixed as contaminants at the time of cleaning. This cleaning liquid suppresses scattering of ammonia positively.

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